



UNIVERSITY OF
ILLINOIS
URBANA-CHAMPAIGN

ME 330: Engineering Materials

Lab - 3

Cold Work and Annealing

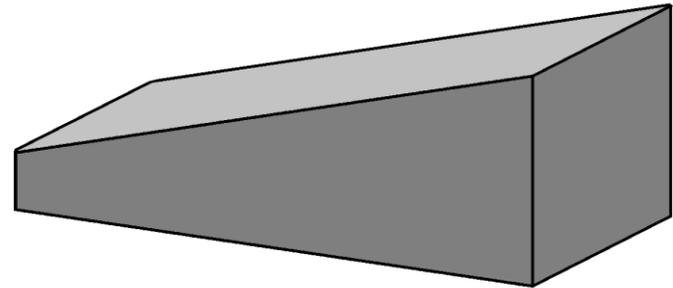


**Grainger College
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Target

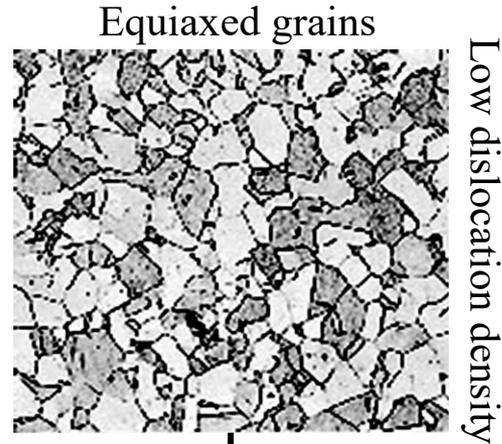
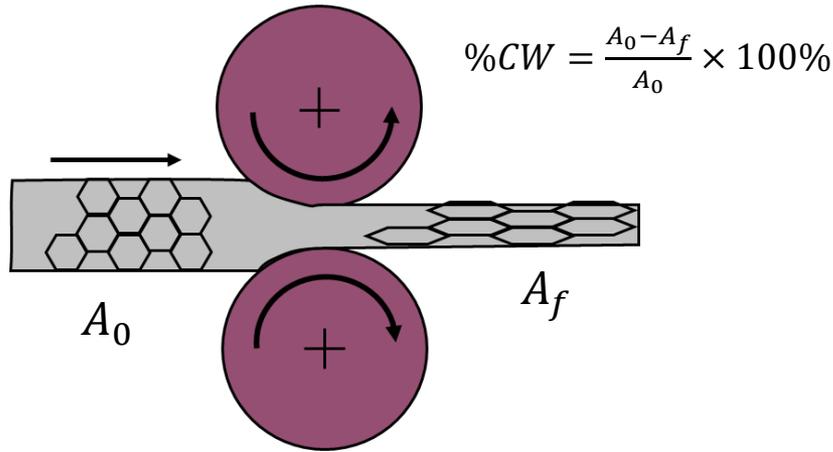


Wedge



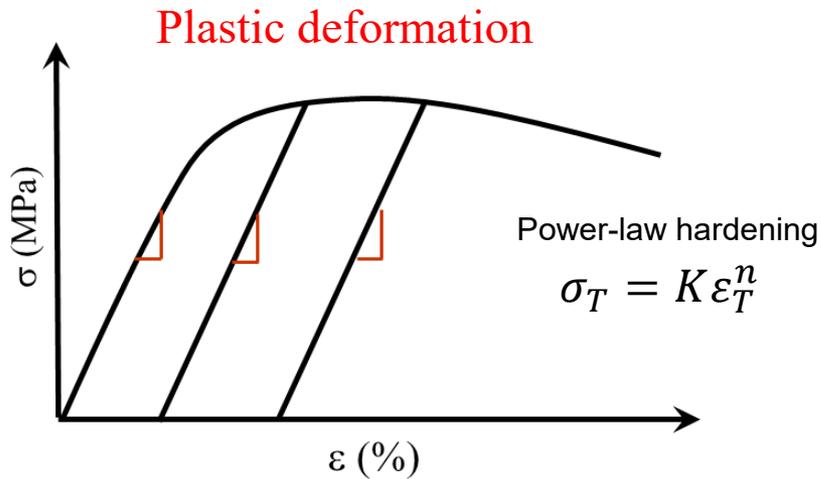
Plate (uniform thickness)

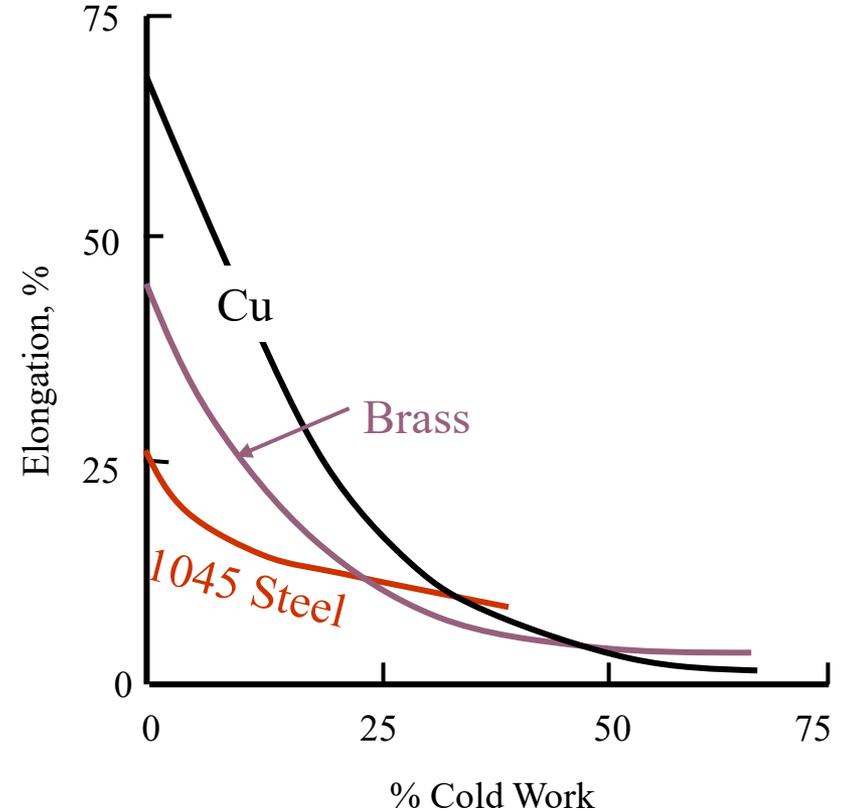
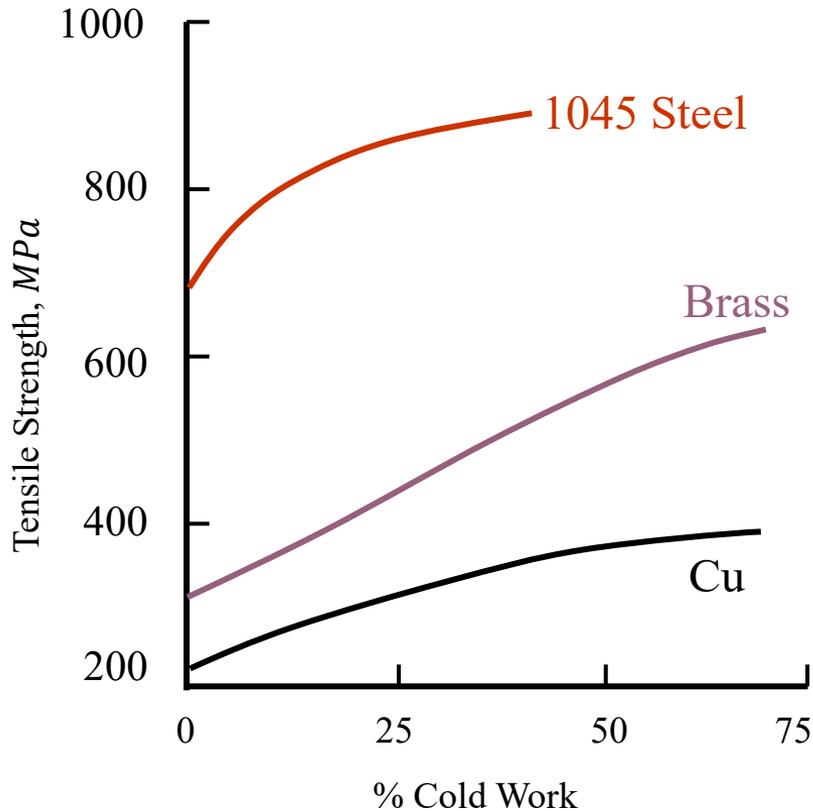
Typical Stress-Strain Curves



Increase in hardness and strength

Decrease in ductility





Cold Work \Rightarrow Higher strength, lower ductility

Annealing Process

- Cold work \Rightarrow dislocation interactions \Rightarrow high strain energy
 - Structure wants to reduce total energy
 - Raise temperature \Rightarrow facilitates atomic motion
- ↓
- Material is heated to a high temperature and held for time:
 - Atoms to rearrange themselves into a lower energy state
 - Diffusion driven process
 - Governed by both *time* and *temperature*:
 - High temperatures and short times
 - Lower temperatures and longer times.
 - Removes the effects of cold work
 - Dislocation density will decrease
 - Grains become equiaxed.

■ ***Recovery***

- Stresses around dislocations are relieved.

■ ***Recrystallization***

- New equiaxed grains nucleate from dislocations.
- Return to nearly pre-cold worked structure & mechanical properties.

■ ***Grain Growth***

- Grain boundaries have high energy.
- Grains grow to reduce overall grain boundary area.
- Grain boundaries migrate due to diffusion of atoms.

